| LTR | ZONE | REVISION | DATE | EQUIP TYPE | APPROVAL |
|---|---|---|---|---|---|
| NC | | SHT. 1. PARTS LIS<br>1. ITEM 8 P/N 251016. WAS R251-013.<br>2. ITEM 10 P/N 251007. WAS R251-007.<br>3. ITEM 11. FLAG NOTE 5 CALLOUT WAS FLAG NOTE 5<br>4. ITEM 13 P/N RM322-206-501-2900 WAS. RM322-206-501-5500.<br>5. ITEM 14 P/N RM322-206-501-5500 WAS. RM372-206-344 5500.<br>6. ITEM 17 QTY 40. WAS 38.<br>7. ITEM 19 QTY 22 WAS 18.<br>8. ADDED ITEM 21.<br>C-8 9. ADDED FLAG NOTE 12.<br><br>SHT. 2.<br>A-8 10. ADDED BALLOON ITEM CALLOUTS 17 AND 19. TO FIELD OF DRAWING.<br>A-8 11. ADDED FLAG NOTE 10 CALLOUT TO DETAIL A.<br>B-8 12. ADDED FLAG NOTE 11 CALLOUT TO FIELD OF DRAWING.<br>D-8 13. ADDED FLAG NOTE 2 CALLOUT TO FIELD OF DRAWING.<br>D-4 14. ADDED FLAG NOTE 12 CALLOUT. AND BALLOON ITEM 1 TO FIELD OF DRAWING.<br>D-3 15. ADDED BALLOON ITEMS 17 AND 19 TO FIELD OF DRAWING.<br>C-2 16. ADDED DETAIL B. | | | |

RELEASED Date Rev Init 1799 NC Q JO

14. COVER C4 to C12 AND F5 WITH GLASS CLOTH TAPE (ITEM 22). SEAL WITH 3140 (ITEM 9).

13. 3M CO. ST PAUL, MN.

12. ON SOLDER SIDE. CONNECTOR J8. CONNECT PIN 154 TO PINS 188-195 OF SAME CONNECTOR. USING WIRE (ITEM 21). AND SOLDER (ITEM 3). KEEP WIRE AS CLOSE TO BOARD AS POSSIBLE. ADHESIVE (ITEM 6) MAY BE USED TO SECURE WIRE. SEE DETAIL B.

11. INSTALL F4 ON SOLDER SIDE OF BOARD. AS SHOWN ON DETAIL A.

10. APPLY 3145 (ITEM 6). STAKING ADHESIVE TO COMPONENTS PER NAS 5300.4 (3J-1). PARA 3J600. 3J601. AND 3J602.

9. RAYCHEM. MINLO PARK. CA.

8. PARK., SUMMERSET. MA.

7. LITTON. DES PLAINES. IL.

6. DOW CORNING. MIDLAND. MI.

5. LITTELFUSE. DES PLAINES. IL.

4. AIRBORN. INC. ADDISON. TX.

3. KEMET ELECTRONICS. GREENVILLE. S.C.

2. PERMANENT INK MARK ASSY DASH NO., S/N AND REV. IN .12 HIGH CHARACTERS WITH 73X WHITE INK PER JSCM-SPEC-M-1. PARA 3.7.8. SERIAL NUMBERS SHALL BE ASSIGNED BY EDCC IN ACCORDANCE WITH EDS MANUAL JPG 8500.4. PARA 3.1.2.

1. INDEPENDENT INK INC., GARDENA. CA.

FLAG NOTES:

10. ALL REFERENCED SPECIFICATIONS AND STANDARDS SHALL BE OF THE LATEST REVISION LEVEL OR AS SPECIFIED IN THE PROCUREMENT DOCUMENT. IN THE CASE OF CONFLICT. THE PROCUREMENT DOCUMENT SHALL TAKE PRECEDENCE.
9. SOLDER SURFACE MOUNT COMPONENTS PER NAS 5300.4 (3M). USING SOLDER PASTE NC-840 (ITEM 2).
8. PRIME PER NAS 5300.4 (3J-1). PARA 3J402 USING 1204 PRIMER (ITEM 20). AFTER MASKING CONNECTORS (J1-J11) ON COMPONENT SIDE. BRUSH APPLY CONFORMAL COATING (ITEM 9). THINNED 2713 NAPTHA (ITEM 18) TO BOTH SIDES OF BOARD; .003 - .009 (.1MM - .2MM) THICK PER NAS 5300.4 (3J-1). PARA 3J500. 3J501. AND 3J502.
7. THIS ASSEMBLY CONTAINS SOME COMPONENTS THAT ARE ESD SENSITIVE; HANDLE PER NASA-STD-8739.7.
6. THIS ASSEMBLY CONTAINS NO FRACTURE CRITICAL PARTS.
5. CLEANLINESS REQUIREMENTS PER SN-C-0005 GC LEVEL.
4. 3140 CONFORMAL COATING TO PRINTED WIRING BOARD .003 - .009 THICK PER NAS 5300.4 (3J-1). CONNECTOR PINS AND .2 MINIMUM FROM EDGE OF MOUNTING HOLES SHALL BE FREE OF CONFORMAL COATING.
3. TORQUE NO. 2 FASTENERS TO 2-3 IN. LBS. ABOVE RUNNING TORQUE.
2. SOLDER COMPONENTS PER NASA/JSC PRC-7001.
1. INTERPRET PER ESD MANUAL JPG 8500.4.

NOTES: UNLESS OTHERWISE SPECIFIED.

| -301 PART NUMBER | DESCRIPTION | REFERENCE DESIGNATOR | SPECIFICATION | ITEM |
|---|---|---|---|---|
| AR | 361-1 | TAPE, GLASS CLOTH | 13 | 22 |
| AR | M22759/22-26-0 | WIRE. STRANDED. BLACK. 26 AWG | TEFLON MIL-W-22759 | 21 |
| AR | 1204 | PRIMER | 8 | 20 |
| 22 | NAS1291C02M | NUT | | 19 |
| AR | 2713 | THINNER. NAPTHA | 8 | 18 |
| 40 | NAS620C2 | WASHER | | 17 |
| 22 | NAS1101E02-8 | CONNECTOR MTG. SCREW | | 16 |
| 2 | WTA14PD9JL | CONNECTOR. 14 PIN SOCKET. WITH FIXED JACK SCREWS | J10. J11 | 4 15 |
| 3 | RM322-206-501-5500 | CONNECTOR. 206 PIN SOCKET. W/GUIDE PINS | J4. J5. J6 | 4 14 |
| 4 | RM322-206-501-2900 | CONNECTOR. 206 PIN SOCKET. WITH FIXED JACK SCREWS | J2. J3. J7. J8 | 4 13 |
| 2 | RM322-152-501-2900 | CONNECTOR. 152 PIN SOCKET W/GUIDE PINS | J1. J9 | 4 12 |
| 2 | RUE500 | FUSE. RESETTABLE. 5A | F3 F4 | 5 11 |
| 2 | 251007 | FUSE. 7A | F5. F6 | 9 10 |
| AR | 3140 | SEALANT | | 6 9 |
| 2 | 251010 | FUSE. 10A | F1. F2 | 5 8 |
| 12 | CDR05BX104BKWS | CAPACITOR. CERAMIC CHIP. .1uF 100V | C1-C12 3 MIL-C-55681 | 7 |
| AR | 3145 | ADHESIVE. RTV | | 6 6 |
| | | | | 5 |
| AR | 73X | INK. MARKING.WHITE | | 1 4 |
| AR | 63/37.025P3REL15 | SOLDER | | QQ-S-571 3 |
| AR | NC-840 | SOLDER PASTE | | 7 2 |
| 1 | SDG46115766-001 | PWB. ICBM BACKPLANE | | 1 |
| REF | SIG46115765 | SCHEMATIC. ICBM BACKPLANE | | |
| | | | | |
| - | -301 | PWBA. | | |

DIMENSIONAL TOLERANCE UNLESS NOTED OTHERWISE 0 PLACE .000 1.010 DO A 83 ANGULAR ± 0 DEG.

SURFACE FINISH IN MICROINCHES MAX UNLESS NOTED OTHERWISE

NEXT ASSY SEG46114201

| SIGNATURES | | DATE |
|---|---|---|
| DR | Z. PALMER | 10/14/98 |
| CHG | | |
| CH | | 10/14/98 |
| APP | | 11/5/98 |
| DE | | 11/5/98 |
| MATL | | 11/5/98 |
| STRESS | | 11/5/98 |
| AUTH | | |

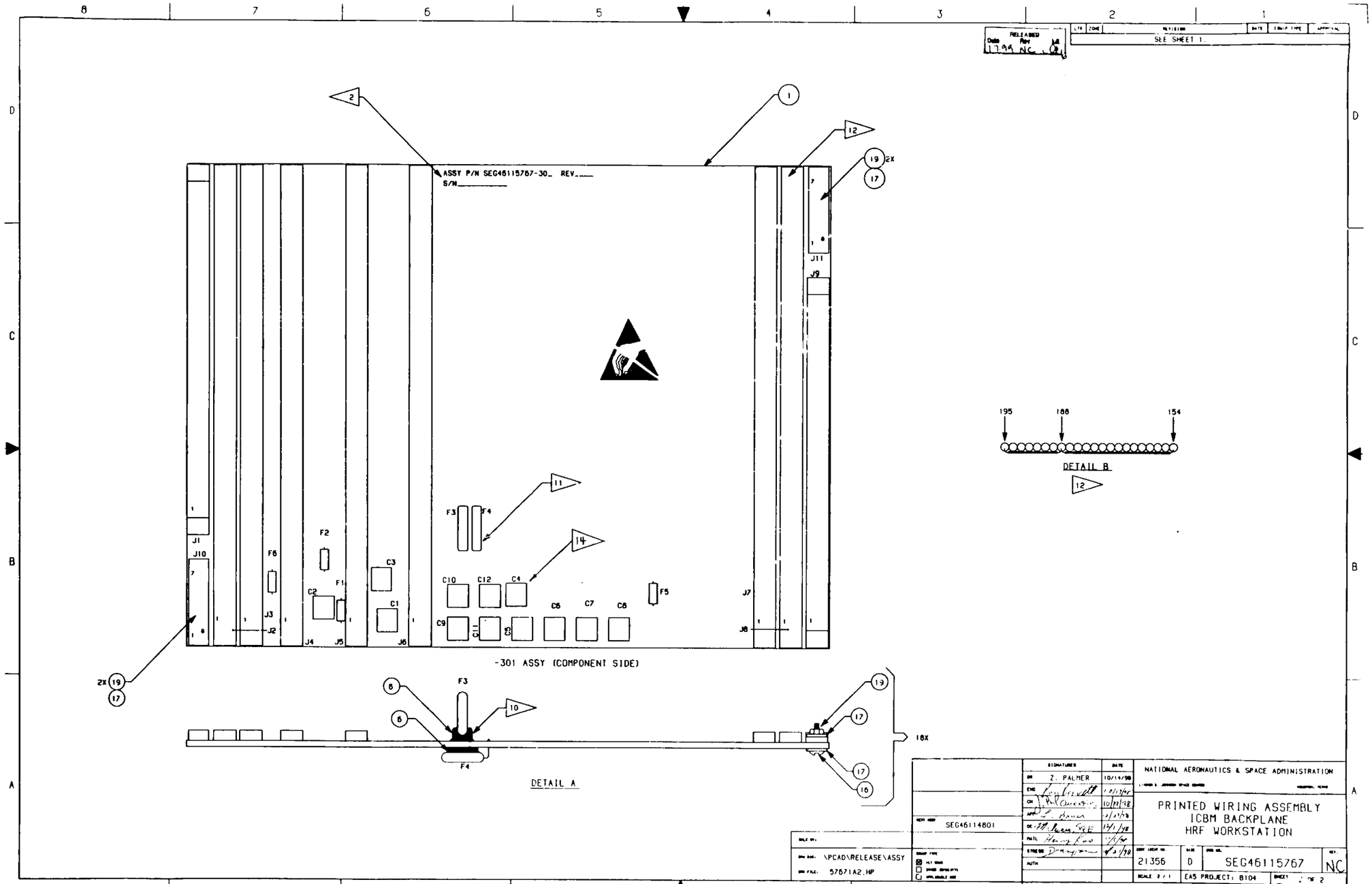
NATIONAL AERONAUTICS & SPACE ADMINISTRATION

PRINTED WIRING ASSEMBLY
ICBM BACKPLANE
HRF WORKSTATION

| SIZE | CODE IDENT NO. | DWG NO. | REV |
|---|---|---|---|
| | 21356 | SEG46115767 | NC |
| SCALE 2/1 | EAS PROJECT. B104 | SHEET 1 OF 2 | |

DWG DIR. \PCAD\RELEASE\ASSY
DWG FILE 57671A1.HP

522


ASSY P/N SEG46115767-30_ REV.___
S/N_____
-301 ASSY (COMPONENT SIDE)
DETAIL A
DETAIL B
195
188
154
SEE SHEET 1.
NATIONAL AERONAUTICS & SPACE ADMINISTRATION
PRINTED WIRING ASSEMBLY
ICBM BACKPLANE
HRF WORKSTATION
Z. PALMER
10/14/98
SEG46114801
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EAS PROJECT: B104

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